

[Opening Lecture]	Low Temperature Bonding for 3D Integration	T. Suga	The University of Tokyo
Role of Low-temperature Bonding in 3D Integration	[keynote] Permanent & Temporary wafer bonding for 3DICs	Jérôme Baro	Yole Développement
	[keynote] Design Flow and Methodologies for 3D Systems Architectures Exploiting Heterogeneous Technologies	Lisa G. McIlrath	R3 Logic Inc.
	[Invite] Heterogeneous 3D Stacking Technologies after Memory Cubes	Hiroaki Ikeda	ASET
	[keynote] Overview of Wafer Direct Bonding Technology: from Substrate Engineering to Heterogeneous Integration Enabled by 3D Wafer Stacking	Ionut Radu	SOITech
Bonding Processes: Overview	[Invite] Low Temperature Metal and Polymer Bonding for Advanced Infrared Imaging Sensor	Drota Temple	RTI
	[Keynote] Wafer-Scale Oxide Fusion Bonding and Wafer Thinning Development for 3D Systems Integration	S. Skordas	IBM Corp
	[Invite] Heterointegration by Wafer Bonding and Layer Splitting	Helmut Baumgart	Old Dominion University
	[Invite] In-situ Observation of Formation of Eutectic Structure between Au and Si	Tadashi Ishida	The University of Tokyo
Bonding Fundamental	[Invite] Passivation of Cu Surface and Its Application in Cu-Cu Bonding for 3D IC	Than Chuan Seng	NTU
	[Invite] Copper-Oxide Reduction for Low-Temperature Wafer Bonding	B. Rebhara	EV Group
Cu-Direct and Cu-Hybrid Bonding	[Invite] Vapor-Assisted Hybrid Bonding of Inorganic/Organic Substrates for 3D Hetero Integration	A. Shigetou	National Institute for Materials Science (NIMS), The University of Tokyo
	[Invite] Fine Pitch Micro-bump Cu/Sn Solid State Diffusion Bonding With and Without Surface Planarization	W. Zhang	IMEC
	Surface Protection of Copper by Self Assembled Monolayer for Low-Temperature Chip Bonding	Lijing Qiu	Kyushu University
	Low Temperature Cu/Cu Direct Bonding Using Formic Gas In-situ Treatment	Wenhua Yan	The University of Tokyo
	Hybrid Solder -Adhesive Bonding Using Simple Resin Planarization Technique for 3D LSI	Masatsugu Nimura	Waseda University
	Cu to Cu Bonding with Cu@Ag Core-shell Nanoparticles	Jenn-Ming Song	National Chung Hsing University
	[keynote] Towards Heterogeneous Optoelectronics Integration by Low Temperature 3D Wafer Bonding	S. J. Ben Yoo	UC Davis
	The Study on the Micro-voids of InP/Si and InP/SiO ₂ Wafer Bonding by Infrared Transmission and Scanning Acoustic Microscopy	Xuan Xiong Zhang	Institute of Microelectronics, Chinese Academy of Sciences
Photonics Applications of Low-temperature Bonding	SOI Platform and III-V Integrated Active Photonic Device by Direct Bonding for Data Communication	Linghan Li	Ritsumeikan University
	Heterogeneous Integrated Subwavelength Plasmonic Waveguide in Near-infrared Region	Yi Wang	Huazhong University of Science and Technology, Institute of Semiconductor, Chinese Academy of Science
	Adhesive Bonding for Integrating Laser Diode and Optical Isolator	Hideki Yokoi	Shibaura Institute of Technology
	AlInAs Selective Oxidation for GaInAsP/Si Hybrid Semiconductor Laser using Surface Activated Bonding	Yusuke Hayashi	Tokyo Institute of Technology
Photonic Applications of Surface Activated Bonding (SAB)	Surface Activated Bonding of Si/Ce:YIG for Waveguide Optical Isolators	Yuya Shoji	Tokyo Institute of Technology
	Fabrication of a New Structured Highly Efficient Wavelength-Conversion Device by Use of the Room-Temperature-Bonding Technique	Tomomi Onda	Chuo University
	Low-Temperature Bonding of Optical Chips using Coined Au Stud Bumps and Its Application to Micro Laser Doppler Velocimeter	Michitaka Yamamoto	The University of Tokyo
	InP/Si Heterogeneous Integration by Low-Temperature Bonding Using Metallic Interlayer	Eiji Higurashi	The University of Tokyo
	Atomic Diffusion Bonding of Wafers in Air with Thin Au Films and Its Application to Optical Devices Fabrication	T. Shimatsu	Tohoku University, KYOCERA KINSEKI Corporation
	Hybrid Integration of LiNbO ₃ Thin Films on Micromachined Si Substrates Using Room-Temperature Transfer Bonding	R. Takigawa	The University of Tokyo, National Institute of Information and Communications Technology (NICT)
	Electrical Properties of Si-based Junctions by SAB	Naoteru Shigekawa	Osaka-City Univ., NTT Photonics Labs., The University of Tokyo
	Comparison of SAB Methods for Room Temperature Bonding of Si Wafers	Keigo Oshikawa	The University of Tokyo, Fuji Electric Co. Ltd.
SAB in Volume Production	[Invite] Clad Material by SAB Method and Its Application in Volume Productions	Hironao Okayama	Toyo Kohan Co., Ltd.
Plasma Activation	[Invite] Low Temperature Bonding Assisted by CMP and/or Plasma Activation	H. Moriceau	LETI
	[Invite] 3D Integration Applications for Low Temperature Direct Bond Technology	Paul Enquist	Ziptronix Inc.
	Low Temperature Plasma Activated Direct Wafer Bonding	T. Plach	Johannes Kepler University Christian Doppler Laboratory for Microscopic and Spectroscopic Material Characterization EVGroup, E. Thallner GmbH
	Variable Bond Strength in Low Temperature Directly Bonded Wafers	V. Masteika	The Open University, Applied Microengineering Ltd.
Temporary Bonding	[Invite] Evolution of Temporary Wafer (De)Bonding Technology Towards Low Temperature	A. Phommahaxay	IMEC
	[Invite] Low Temperature Process Evaluation for 3DIC Integrated Thin Wafer Handling	Yu-Hua Chen	ITRI
Self-Assembly	Temporary-Bonding and LowTemp® Debonding Technology for Various Applications	Masaya Kawano	EV Group E. Thallner GmbH
	Self-Assembly-Based 3D Integration Technologies	T. Fukushima	Tohoku University
New Bonding Process	Assembly of 20µm Pitch Cu/Sn Micro-bumps Using High Speed Capillary Self-alignment	Philippe Soussan	IMEC
	Atomic Diffusion Bonding with Thin Nanocrystalline Metal Films in Vacuum and in an Inert Gas	T. Shimatsu	Tohoku University
	Water Vapor Containing Plasma Activation for Room-temperature Bonding	Chenxi Wang	The University of Tokyo
	Surface Activated Bonding and Transfer of Carbon Nanotube Bumps to Au substrates	Masahisa Fujino	The University of Tokyo, FUJITSU Laboratories Ltd.
New Metal Bonding Process	Direct Bonding of Polymer to Glass Wafers using Surface Activated Bonding (SAB) Method at Room Temperature	Takashi Matsumae	The University of Tokyo, Lantech Service Co., Ltd.
	Low Temperature Metal Interdiffusion Bonding for Micro Devices	J. Frömel	Fraunhofer ENAS, Tohoku University
	Room-Temperature Microjoining Using Ultrasonic Bonding of Compliant Bump	Keiichiro Iwanabe	Kyushu University
	Low Temperature Au-Au Flip Chip Bonding with VUV/O ₃ Treatment for 3D Integration	Akiko Okada	Waseda University
	Low-Temperature Wafer Bonding Using Sub-Micron Gold Particles for Wafer-Level MEMS Packaging	H. Ishida	SUSS MicroTec K
	Low Temperature Crack-less Solder Bonding Technique Using Self-propagating Exothermic Nanolayers	T. Morikaku	University of Hyogo
Polymer and Film Application	Low Temperature Bonding Method Using Metal Microcone Arrays	Qin Lu	Shanghai Jiao Tong University
	[Invite] Ultrasonic Bonding of NCF/ACF	Kyung W. Paik	KAIST
MEMS and Other Applications	[Invite] Wafer-Level Heterogeneous 3D Integration for MEMS and NEMS	Frank Niklaus	KTH Royal Institute of Technology
	[Invite] Low Temperature Wafer Bonding for MEMS-Processes and 3D-Integration	Roy Knechtel	XFAB
	Low Temperature Assembly Method of Microfluidic Bio-molecules Detection System	S. van Loo	University of Liège
	A Hierarchic Bonding Procedure for the Assembly of Micro Confocal Microscope	C. Jia	Fraunhofer ENAS, Tohoku University
Testing and Evaluation	A Versatile Optical System for Metrology and Defects Inspection of 3D Integration Processes	S. Perrot	Univ Paris-Sud, Institut d'Electronique Fondamentale
	Investigation of Si/SiO ₂ Bonding Energy Using Recess Test Structure	Aapo Varpul	VTT Technical Research Centre of Finland
	Mechanical Reliability of Micron-size Solder Joints Fabricated by Explosively Reacting Nanolayers	T. Fuji	University of Hyogo